

ABSTRACT OF THE DISCLOSURE

A device mounting method capable of efficiently, accurately arraying micro-devices on a circuit board is provided. The method includes a device separating step of separating a plurality of LED chips, which have been arrayed with a specific period on a wafer, into individual LED chips while keeping the arrayed state of the LED chips as it is, a device re-arraying step of handling the individually separated LED chips so as to re-array the LED chips at intervals of a value equivalent to the period multiplied by a specific magnification, and a device transferring step of transferring the re-arrayed LED chips on a mounting board while keeping the re-arrayed state of the LED chips as it is.